

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in this application:

**Listing Of The Claims:**

1. (Currently Amended) A method for producing a conductive layered coating on an insulating substrate, comprising:

equipping, in selected regions, at least one surface of an electrically insulating substrate with a coating of an electrically highly conductive first metal, the coating being structured as conductor paths;

cleaning the at least one coated surface;

seeding the coating with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the coating seeded with the seeds of the second metal;

firing the substrate deposited with the layer of the second metal to form the conductive layered coating, ~~the firing being performed at a temperature below the melting point of the first metal, the second metal and the alloy, the firing being performed so that the~~  
first metal is diffused with the second metal; and

contacting a gold bonding wire to the conductive layered coating, wherein:

the substrate includes a low-temperature co-fired ceramic (LTCC),

the first metal includes silver, and

the second metal includes palladium.

2. (Canceled).

3. (Canceled).

4. (Previously Presented) The method as recited in Claim 1, wherein:

in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy.

5. (Previously Presented) The method as recited in Claim 1, wherein:

in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results.

6. (Original) The method as recited in Claim 1, wherein:

the seeding and the depositing are performed according to an electroless procedure.

7. (Original) The method as recited in Claim 1, wherein:

The firing is performed at a temperature between 830 and 870°C.

8. (Original) The method as recited in Claim 1, wherein:

the firing is performed at a temperature of 850°C.

9-10. (Canceled).

11. (Previously Presented) A method for producing a conductive layered coating on an electrically insulating substrate, comprising:

equipping, in selected regions, at least one surface of the electrically insulating substrate with a coating of a first metal structured as a conductor path;

cleaning the at least one coated surface;

seeding the at least one coated surface with seeds of a second metal;

depositing a layer including an alloy of the second metal onto the at least one seeded coated surface; and

firing the substrate deposited with the layer to form the conductive layered coating, the firing being performed at a temperature below the melting point of the first metal, the second metal and the alloy.

12. (Previously Presented) The method of claim 11, wherein the substrate includes an LTCC;

13. (Previously Presented) The method of claim 12, wherein the first metal includes silver and the second metal includes palladium.

14. (Previously Presented) The method of claim 13, further comprising:

contacting a gold bonding wire to the conductive coating.

15. (Currently Amended) The method of Claim 13, wherein the low-temperature co-fired ceramic (LTCC) is a glass-ceramic mixture that, together with metallization pastes made

from silver (Ag), silver-~~palladium~~ palladium (AgPd) or gold (Au), is fired at a ~~relatively low~~ temperature that is below the melting point of the metallization pastes.

16. (Currently Amended) The method of Claim 13, wherein a nickel bath is not used and a gold bath is not used, and wherein the low-temperature co-fired ceramic (LTCC) is a glass-ceramic mixture that, together with metallization pastes made from silver (Ag), silver-~~palladium~~ palladium (AgPd) or gold (Au), is fired at a ~~relatively low~~ temperature that is below the melting point of the metallization pastes.

17. (Previously Presented) The method of Claim 16, wherein:

in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy,

in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results, and

the firing is performed at a temperature between 830 and 870°C.

18. (Previously Presented) The method of Claim 17, wherein the seeding and the depositing are performed according to an electroless procedure, and the firing is performed at a temperature of 850°C.

19. (Currently Amended) The method of Claim 1, wherein the low-temperature co-fired ceramic (LTCC) is a glass-ceramic mixture that, together with metallization pastes made from silver (Ag), silver-~~palladium~~ palladium (AgPd) or gold (Au), is fired at a ~~relatively low~~ temperature that is below the melting point of the metallization pastes.

20. (Currently Amended) The method of Claim 1, wherein a nickel bath is not used and a gold bath is not used, and wherein the low-temperature co-fired ceramic (LTCC) is a glass-ceramic mixture that, together with metallization pastes made from silver (Ag), silver-~~palladium~~ palladium (AgPd) or gold (Au), is fired at a ~~relatively low~~ temperature that is below the melting point of the metallization pastes.

21. (Previously Presented) The method of Claim 20, wherein:

in the depositing of the layer of the second metal, palladium is deposited at a ratio of from 0.1 to 50% percent by weight of the alloy,

in the depositing of palladium, the palladium is deposited in such a way that a concentration of greater than 20% percent by weight palladium in the alloy results, and

the firing is performed at a temperature between 830 and 870°C.

22. (Previously Presented) The method of Claim 21, wherein the seeding and the depositing are performed according to an electroless procedure, and the firing is performed at a temperature of 850°C.